

Electronic Acknowledgement Receipt

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Title of Invention:	METHOD OF FORMING STRAINED SILICON MATERIALS WITH IMPROVED THERMAL CONDUCTIVITY
First Named Inventor/Applicant Name:	Stephen W. Bedell
Customer Number:	32074
Filer:	Yuanmin Cai/Nicole Barrese
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Document Number	Document Description	File Name	File Size(Bytes)	Multi Part /.zip	Pages (if appl.)
1	Amendment After Final	FIS920040069RESPONSE.pdf	109453	no	5

Warnings:

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